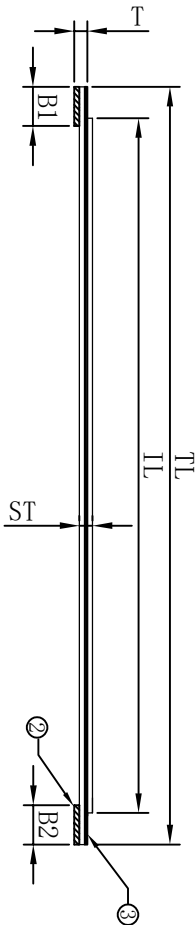
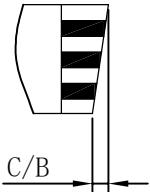


STRUCTURE		
NO	ITEM NAME	SPECIFICATION
1	INSULATION	印字UL20706 60um
	(绝缘层)	空白60um
印字		
2	P/TAPE (补强板)	205um
3	CONDUCTOR (镀锡线)	THICKNESS 0.05
		WIDTH 0.8
	CONDUCTOR (导体镀层)	PLATED Sn(40u")
		PLATED MIN



DIMENSION			
PITCH (间距)	P	1.25	±0.1
SPAN (全间距)	SP	13.75	±0.1
WIDTH(总宽度)	W	16.25	±0.15
MARGIN(边距)	M	1.25	±0.15
	M1		
INSERT THICKNESS (插入厚度)	T	0.31	±0.03
SURFACE THICKNESS (线身厚度)	ST	0.17	±0.03
PROTECTOR LENGTH (补强板长度)	B1	32.0	±2.0
	B2	8.0	±2.0
STRIP LENGTH (金手指长度)	S1	5.0	±1.0
	S2	5.0	±1.0
INSULATION LENGTH (绝缘层长度)	I.L	740.0	±3.0
TOTAL LENGTH (产品总长度)	T.L	750.0	±3.0
NO of PIN (导体数量)	12P		



NOTES:

- 成品之两端内外CB为0—0.3mm
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HECON P/N				HC-FPC-125-12P-XXX-A01			
HECON 东莞市禾康电子有限公司				DONGGUAN HECON ELECTRONICS CO., LTD			
TITLE				1.25*12P*750-5/5/32/8 A			
APPROVED							
CHECKED							
DRAWN				Bo Feng			
SER				DESCRIPTION			
CHK				DATE			
UNIT				mm			
SIZE				A4			
REV							
SHEET				1/1			